

In re Patent Application of:

ZENG

Serial No. 09/844,347

Filing Date: April 27, 2001

In the Claims:

Claims 1-22 (Cancelled).

23. (Currently Amended) A MOSFET comprising:
a semiconductor layer having a trench therein;
a gate conducting layer in a lower portion of the
trench;

a dielectric layer in an upper portion of the trench
~~and extending outwardly from said semiconductor layer, the~~
~~outwardly extending dielectric layer having sidewalls aligned~~
~~with sidewalls of the trench;~~

source regions adjacent said dielectric layer ~~the~~
~~outwardly extending dielectric layer;~~ and

source/body contact regions laterally spaced apart
from said gate conducting layer and non-interruptibly
contacting said source ~~regions~~ regions;

said dielectric layer extending outwardly from said
semiconductor layer, said source regions, and said source/body
contact regions and having sidewalls aligned with sidewalls of
the trench.

24. (Previously Amended) A MOSFET according to Claim
23, further comprising a source electrode on said source
regions and on said dielectric layer.

25. (Original) A MOSFET according to Claim 24,
further comprising at least one conductive via between said
source electrode and said source/body contact regions.

26. (Original) A MOSFET according to Claim 23,

In re Patent Application of:

ZENG

Serial No. **09/844,347**

Filing Date: **April 27, 2001**

wherein a portion of said source regions include a recess over said source/body contact regions.

27. (Original) A MOSFET according to Claim 23, wherein a portion of said source regions include an opening exposing said source/body contact regions; and further comprising a source electrode on said source regions, on said dielectric layer, and on said source/body contact regions.

28. (Original) A MOSFET according to Claim 23, wherein said outwardly extending dielectric layer extends from said source regions equal to or less than about 1 micron.

29. (Original) A MOSFET according to Claim 23, wherein the gate is recessed in the trench within a range of about 0.2 to 0.8 microns from an opening thereof.

30. (Original) A MOSFET according to Claim 23, wherein said source/body contact regions are recessed within said semiconductor layer adjacent said source regions.

31. (Original) A MOSFET according to Claim 30, wherein an upper surface of the recess is equal to or less than a depth of about 1 micron from a surface of the semiconductor layer.

32. (Currently Amended) A MOSFET comprising:
a semiconductor layer having a trench therein;
a gate dielectric layer lining the trench;
a gate conducting layer in a lower portion of the

In re Patent Application of:

ZENG

Serial No. 09/844,347

Filing Date: April 27, 2001

trench;

a dielectric layer in an upper portion of the trench and ~~extending outwardly from said semiconductor layer, the outwardly extending dielectric layer having sidewalls aligned with sidewalls of the trench;~~

source regions adjacent said dielectric layer ~~the outwardly extending dielectric layer;~~

source/body contact regions laterally spaced from said gate conducting layer and non-interruptibly contacting said source regions;

said dielectric layer extending outwardly from said semiconductor layer, said source regions, and said source/body contact regions and having sidewalls aligned with sidewalls of the trench;

a source electrode on said source regions and on said dielectric layer; and

at least one conductive via between said source electrode and said source/body contact regions.

33. (Previously Added) A MOSFET according to Claim 32, wherein a portion of said source regions include a recess over said source/body contact regions.

34. (Previously Added) A MOSFET according to Claim 32, wherein said outwardly extending dielectric layer extends from said source regions equal to or less than about 1 micron.

35. (Previously Added) A MOSFET according to Claim 32, wherein said gate conducting layer is recessed in the trench within a range of about 0.2 to 0.8 microns from an

In re Patent Application of:

ZENG

Serial No. **09/844,347**

Filing Date: **April 27, 2001**

opening thereof.

36. (Currently Amended) A MOSFET comprising:
a semiconductor layer having a trench therein;
a gate dielectric layer lining the trench;
a gate conducting layer in a lower portion of the
trench;

a dielectric layer in an upper portion of the trench
and extending outwardly from said semiconductor layer, the
outwardly extending dielectric layer having sidewalls aligned
with sidewalls of the trench;

source regions adjacent ~~said the outwardly extending~~
dielectric layer and including an opening therein; and

source/body contact regions laterally spaced from
said gate conducting layer and non-interruptibly contacting
said source regions, said source/body contact regions being
exposed by the opening in said source ~~regions~~ regions;

said dielectric layer extending outwardly from said
semiconductor layer, said source regions, and said source/body
contact regions and having sidewalls aligned with sidewalls of
the trench.

37. (Previously Added) A MOSFET according to Claim
36, further comprising a source electrode on said source
regions, on said dielectric layer, and on said source/body
contact regions.

38. (Previously Added) A MOSFET according to Claim
36, wherein said outwardly extending dielectric layer extends
from said source regions equal to or less than about 1 micron.

In re Patent Application of:

ZENG

Serial No. 09/844,347

Filing Date: April 27, 2001

39. (Previously Added) A MOSFET according to Claim 36, wherein said gate conducting layer is recessed in the trench within a range of about 0.2 to 0.8 microns from an opening thereof.